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APPLICATION NO. FILING DATE		FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO. 9683	
10/064,766 08/15/2002		Chun-Ling Peng	8043-US-PA		
31561	7590 06/24/2004		EXAMINER		
JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE 7 FLOOR-1, NO. 100			DEO, DUY VU NGUYEN		
	T ROAD, SECTION 2	ART UNIT	PAPER NUMBER		
TAIPEI, 100 TAIWAN			1765		
			DATE MAILED: 06/24/2004		

Please find below and/or attached an Office communication concerning this application or proceeding.

		Ap	plication No.	Applicant(s)			
		10	0/064,766	PENG, CHUN-LING			
(Office Action Summary	Ex	aminer	Art Unit			
			yVu n Deo	1765			
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply							
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely. - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).							
Status							
1)⊠ Re:	sponsive to communication(s) file	ed on <u>15 Augus</u>	<u>st 2002</u> .				
2a)☐ Thi	is action is FINAL .	2b)⊠ This acti	This action is non-final.				
,							
Disposition	of Claims						
4) Claim(s) 1-10 is/are pending in the application. 4a) Of the above claim(s) is/are withdrawn from consideration. 5) Claim(s) 1-4 is/are allowed. 6) Claim(s) 5-10 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or election requirement. Application Papers							
9) The specification is objected to by the Examiner:							
10)⊠ The drawing(s) filed on <u>15 August 2002</u> is/are: a)⊠ accepted or b)⊡ objected to by the Examiner.							
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).							
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.							
Priority under 35 U.S.C. § 119							
12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) ☐ All b) ☐ Some * c) ☐ None of: 1. ☐ Certified copies of the priority documents have been received. 2. ☐ Certified copies of the priority documents have been received in Application No 3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received.							
Attachment(s)							
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 4) Interview Summary (PTO-413) Paper No(s)/Mail Date.							
3) Information	Draftsperson's Patent Drawing Review (i on Disclosure Statement(s) (PTO-1449 or o(s)/Mail Date			Patent Application (PTO-152)			

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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- (e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

The changes made to 35 U.S.C. 102(e) by the American Inventors Protection Act of 1999 (AIPA) and the Intellectual Property and High Technology Technical Amendments Act of 2002 do not apply when the reference is a U.S. patent resulting directly or indirectly from an international application filed before November 29, 2000. Therefore, the prior art date of the reference is determined under 35 U.S.C. 102(e) prior to the amendment by the AIPA (pre-AIPA 35 U.S.C. 102(e)).

2. Claims 5-7 are rejected under 35 U.S.C. 102(e) as being anticipated by Wu (US 6,482,744).

Wu describes a method for etching a substrate comprising: loading the substrate on a susceptor in an etching chamber (col. 2, line 30-35); performing etching with a height of the susceptor in the etching being adjusted to an optimum height that results uniform and even

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etching of the material (col. 1, line 40-45; col. 3, line 16-40). The uniform and even etching would read on claimed minimum deviation of etching depth.

Referring to claim 6, the support pole 107 that moving up and down to adjust the height of the substrate would read on claimed shaft under the susceptor (col. 2, line 18-29).

Referring to claim 7, the material etched included oxide layer (col. 3, line 50-61). This would read on claimed silicon oxide layer.

Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 4. Claims 8-10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Wu.

Unlike claimed invention, Wu doesn't describe the etching method is for rounding a corner of an opening. However, he teaches that the method can be used with any etching process that requires uniform etching over the entire surface of the substrate (col. 4, line 59-63).

Therefore, it would have been obvious to one skilled in the art at the time of the invention to use the method for any etching including rounding corner of an opening in order to provide an uniform etching over the entire surface of the wafer.

Allowable Subject Matter

5. Claims 1-4 are allowed because applied prior art, Wu, doesn't describe repeating the 2 steps (in claim 1) with respect to various height to obtain several sets of corresponding date for different heights and selecting the height resulting in a minimum deviation of etching depth as a

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height to perform a normal etching process. Wu describes the uniform etching (minimum deviation of etching depth) is achieved by etching the substrate at different heights.

6. Any inquiry concerning this communication or earlier communications from the examiner should be directed to DuyVu n Deo whose telephone number is 571-272-1462. The examiner can normally be reached on 6:00-3:30; with alternate Friday off.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine Norton can be reached on 571-272-1465. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

DVD 6/22/04